

RF POWER MOSFETS N-CHANNEL ENHANCEMENT MODE

150V 350W 45MHz

The ARF469A and ARF469B comprise a symmetric pair of common source RF power transistors designed for pushpull scientific, commercial, medical and industrial RF power amplifier applications up to 45 MHz. They have been optimized for both linear and high efficiency classes of operation.

• Specified 150 Volt, 40.68 MHz Characteristics:

Output Power = 350 Watts.

Gain = 16dB (Class AB)

Efficiency = 75% (Class C)

- Low Cost Common Source RF Package.
- Low Vth thermal coefficient.
- Low Thermal Resistance.
- Optimized SOA for Superior Ruggedness.

MAXIMUM RATINGS

All Ratings: $T_C = 25^{\circ}C$ unless otherwise specified.

Symbol	Parameter	Ratings	UNIT	
V _{DSS}	Drain-Source Voltage	500	Volts	
V_{DGO}	Drain-Gate Voltage	500	Volto	
I _D	Continuous Drain Current @ T _C = 25°C	30	Amps	
V _{GS}	Gate-Source Voltage	±30	Volts	
P _D	Total Power Dissipation @ T _C = 25°C	445	Watts	
R _{eJC}	Junction to Case	0.28	°C/W	
T _J ,T _{STG}	Operating and Storage Junction Temperature Range	-55 to 150	- °C	
T_L	Lead Temperature: 0.063" from Case for 10 Sec.	300		

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV _{DSS}	Drain-Source Breakdown Voltage ($V_{GS} = 0V$, $I_D = 250 \mu A$)	500			Volts
R _{DS(ON)}	Drain-Source On-State Resistance $(V_{GS} = 10V, I_D = 15A)$		0.25	0.28	ohms
	Zero Gate Voltage Drain Current ($V_{DS} = 500V, V_{GS} = 0V$)			25	
I _{DSS}	Zero Gate Voltage Drain Current ($V_{DS} = 400V$, $V_{GS} = 0V$, $T_{C} = 125$ °C)			250	μA
I _{GSS}	Gate-Source Leakage Current $(V_{GS} = \pm 30V, V_{DS} = 0V)$			±100	nA
9 _{fs}	Forward Transconductance $(V_{DS} = 25V, I_{D} = 6.5A)$		8		mhos
V _{GS} (TH)	Gate Threshold Voltage $(V_{DS} = V_{GS}, I_{D} = 1mA)$	2		4	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

DYNAMIC CHARACTERISTICS

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C _{iss}	Input Capacitance	V _{GS} = 0V		2300		
C _{oss}	Output Capacitance	V _{DS} = 150V f = 1 MHz		250		pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1/11/12		125		

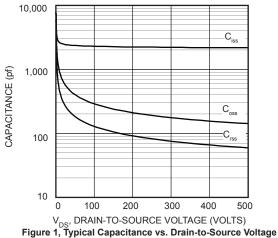
FUNCTIONAL CHARACTERISTICS

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
G _{PS}	Common Source Amplifier Power Gain	f = 40.68 MHz	14	16		dB
η	Drain Efficiency	$V_{GS} = 2.5V$ $V_{DD} = 150V$	70	75		%
Ψ	Electrical Ruggedness VSWR 10:1	P _{out} = 350W	No Deg	radation	in Output	Power

① Pulse Test: Pulse width < 380μ S, Duty Cycle < 2%

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TYPICAL PERFORMANCE CURVES



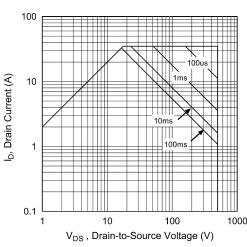
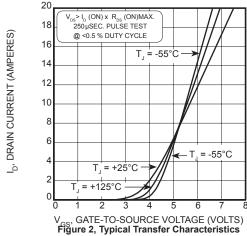


Figure 3, Typical Maximum Safe Operating Area



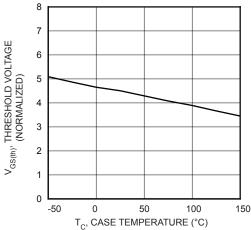
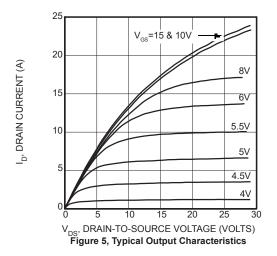


Figure 4, Typical Threshold Voltage vs Temperature



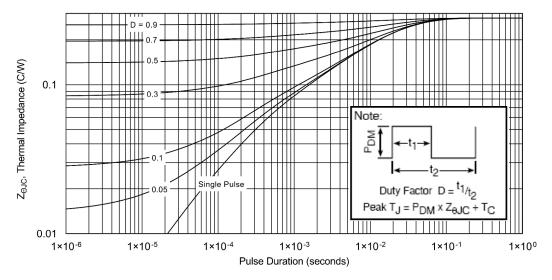
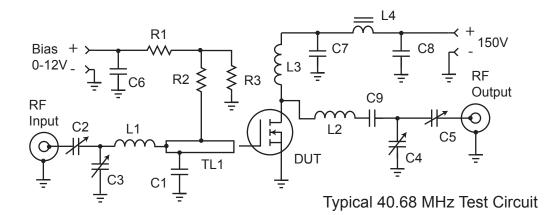


FIGURE 6, MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs PULSE DURATION

Table 1 - Typical Class AB Large Signal Input - Output Impedance

Freq. (MHz)	$Z_{in}(\Omega)$	$Z_{OL}(\Omega)$
2.0	18 - j 10.8	30 - j 1.5
13.5	1.3 - j 4.8	26- j 9.6
27.1	0.4- j 2.4	18 - j 13.1
40.7	0.2 - j 1.4	12 - j 12.4

 $Z_{_{IN}}$ - Gate shunted with 25 Ω I $_{_{dq}}$ = 100mA $Z_{_{OL}}$ - Conjugate of optimum load for 300 Watts output at V $_{_{dd}}$ =150V



C1 -- 2200pF ATC 700B C2-C5 -- Arco 465 Mica trimmer C6-C8 -- .1 µF 500V ceramic chip C9 -- 3x 2200 pF 500V chips COG

Drain

L1 -- 4t #22 AWG .25"ID .25 "L ~87nH L2 -- 5t #16 AWG .312" ID .35"L ~176nH

TO-264 (L) Package Outline

L3 -- 10t #24 AWG .25"ID ~.5μH L4 -- VK200-4B ferrite choke 3μH R1- R3 -- $1k\Omega$ 0.5 Ω Carbon TL1 -- 34Ω t-line 0.175" x 1" C1 .45" from gate pin. PCB -- 0.062" FR4, Er=4.7

4.60 (.181) 5.21 (.205) 1.80 (.071) 2.01 (.079) 1.80 (.071) 2.01 (.079) 3.10 (.122) 3.48 (.137) Dimensions in Millimeters and (Inches) NOTE: These two parts comprise a symmetric pair of RF power transistors and meet the same electrica

2.29 (.090) 2.69 (.106)

5.45 (.215) BSC

Dimensions in Millimeters and (Inches)

25.48 (1.003) 26.49 (1.043)

19.81 (.780) 21.39 (.842)





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